

# FDT3N40

## N-Channel UniFET™ MOSFET

400 V, 2.0 A, 3.4

### Features

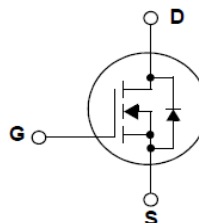
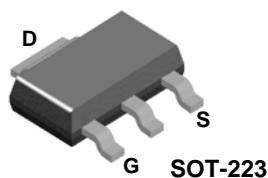
- $R_{DS(on)} = 3.4 \Omega$  (Max.) @  $V_{GS} = 10 V$ ,  $I_D = 1.0 A$
- Low Gate Charge (Typ. 4.5 nC)
- Low  $C_{rss}$  (Typ. 3.7 pF)
- 100% Avalanche Tested

### Applications

- LCD/LED TV
- Lighting
- Uninterruptible Power Supply

### Description

UniFET™ MOSFET is Fairchild Semiconductor®'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



### Absolute Maximum Ratings

Symbol	Parameter	FDT3N40	Unit
$V_{DSS}$	Drain-Source Voltage	400	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ C$ ) - Continuous ( $T_C = 100^\circ C$ )	2.0 * 1.2 *	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	8.0 *	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	46	mJ
$I_{AR}$	Avalanche Current (Note 1)	2	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	0.2	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ C$ ) - Derate above $25^\circ C$	2 0.02	W W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ C$

\* Drain current limited by maximum junction temperature

### Thermal Characteristics

Symbol	Parameter	FDT3N40	Unit
$R_{\theta JA}$ *	Thermal Resistance, Case-to-Sink Typ.	60	$^\circ C/W$

\* Surface Mounted on JESD51-3 Board,  $T < 0.1$ sec.

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDT3N40	FDT3N40TF	SOT-223	330mm	12mm	4000

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

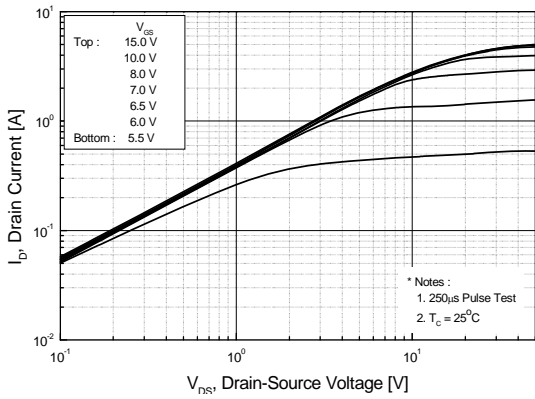
Symbol	Parameter	Conditions	Min.	Typ.	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	400	--	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C	--	0.4	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 400V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 320V, T <sub>C</sub> = 125°C	--	--	1 10	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	3.0	--	5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1A	--	2.8	3.4	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 1A (Note 4)	--	2	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	--	173	225	pF
C <sub>oss</sub>	Output Capacitance		--	30	40	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	3.7	6	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 200V, I <sub>D</sub> = 2A R <sub>G</sub> = 25Ω  (Note 4, 5)	--	10	30	ns
t <sub>r</sub>	Turn-On Rise Time		--	30	70	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	10	30	ns
t <sub>f</sub>	Turn-Off Fall Time		--	25	60	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 320V, I <sub>D</sub> = 2A V <sub>GS</sub> = 10V  (Note 4, 5)	--	4.5	6	nC
Q <sub>gs</sub>	Gate-Source Charge		--	1.2	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	2	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		--	--	2	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		--	--	8	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 2A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 2A di <sub>F</sub> /dt = 100A/μs  (Note 4)	--	210	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	0.75	--	μC

### NOTES:

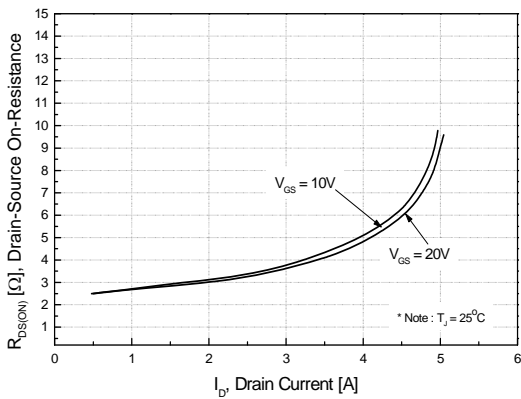
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 10mH, I<sub>AS</sub> = 2A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C
3. I<sub>SD</sub> ≤ 2A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C
4. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%
5. Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

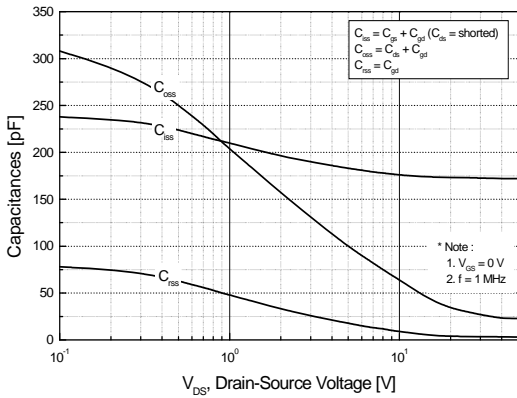
**Figure 1. On-Region Characteristics**



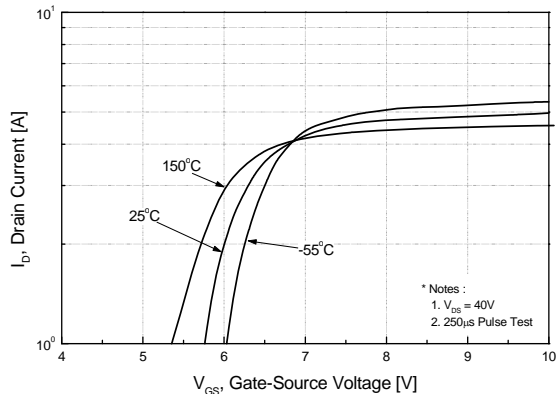
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



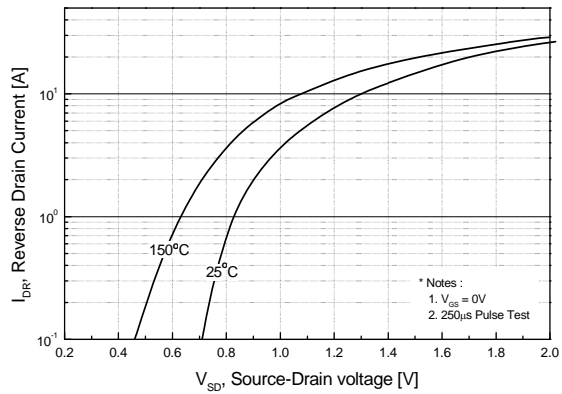
**Figure 5. Capacitance Characteristics**



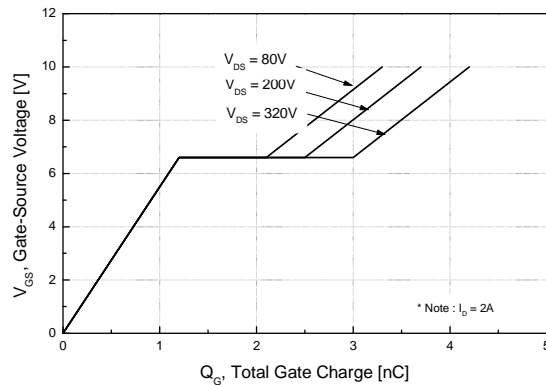
**Figure 2. Transfer Characteristics**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

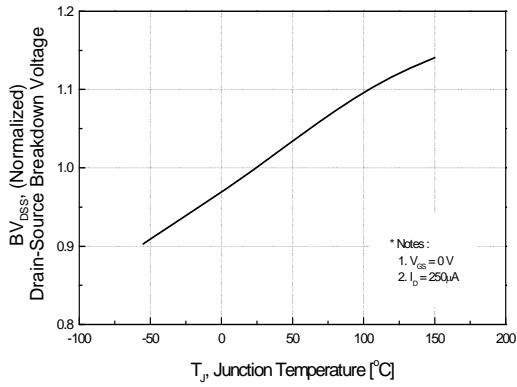


**Figure 6. Gate Charge Characteristics**

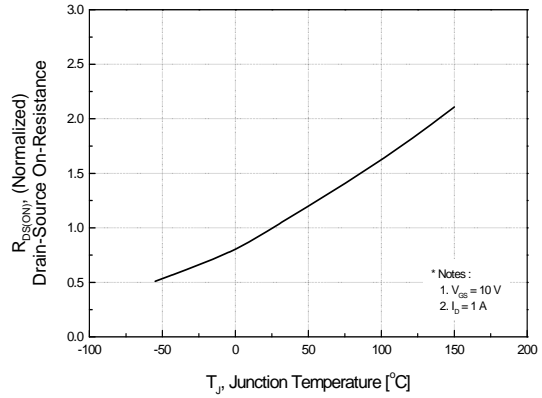


**Typical Performance Characteristics** (Continued)

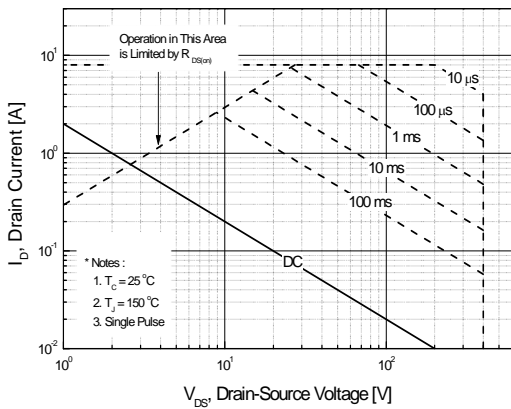
**Figure 7. Breakdown Voltage Variation vs. Temperature**



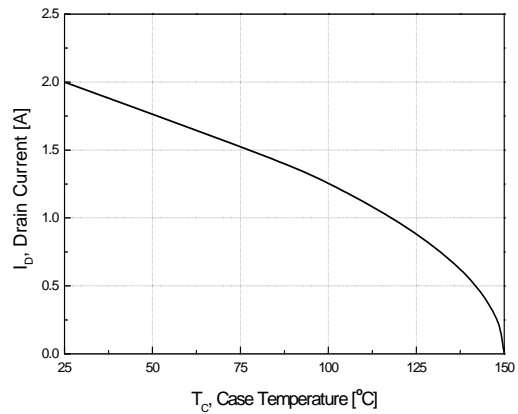
**Figure 8. On-Resistance Variation vs. Temperature**



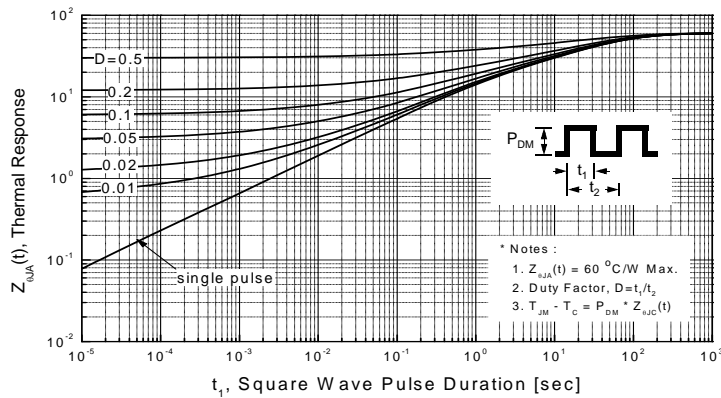
**Figure 9. Maximum Safe Operating Area**



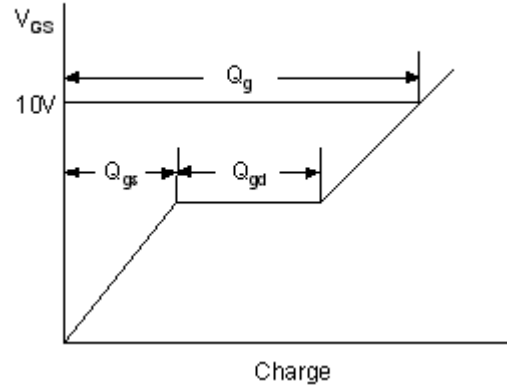
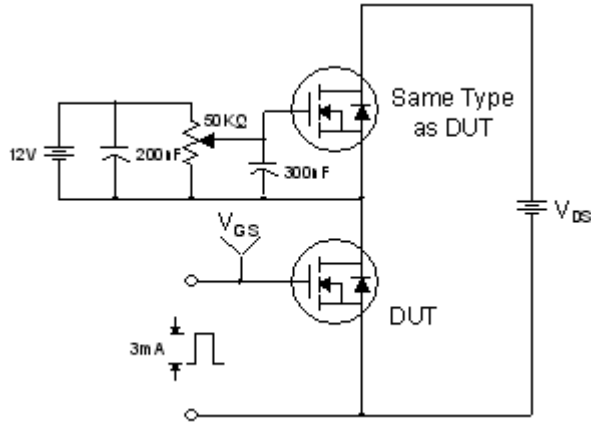
**Figure 10. Maximum Drain Current vs. Case Temperature**



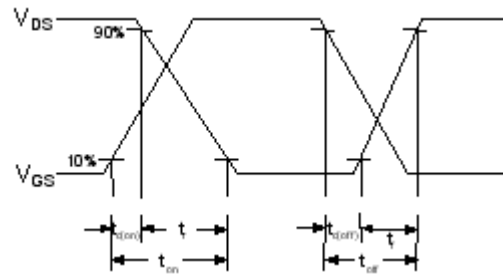
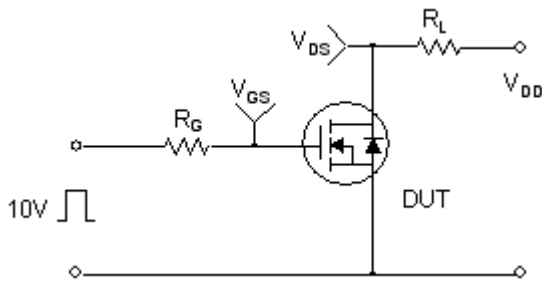
**Figure 11. Transient Thermal Response Curve**



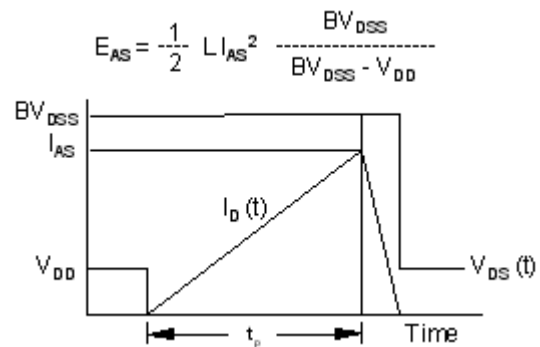
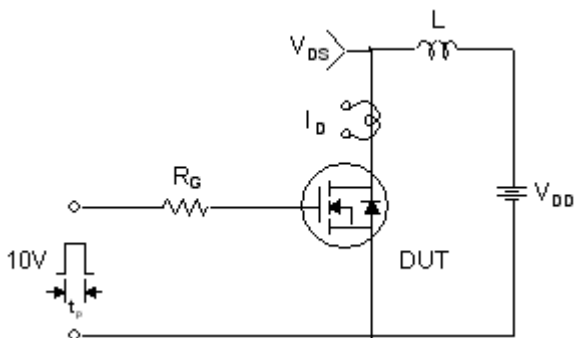
**Gate Charge Test Circuit & Waveform**



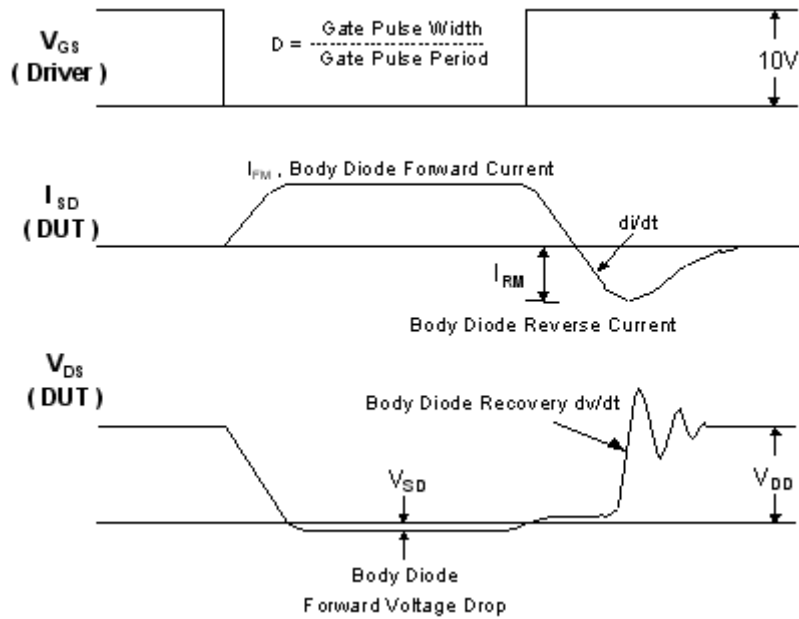
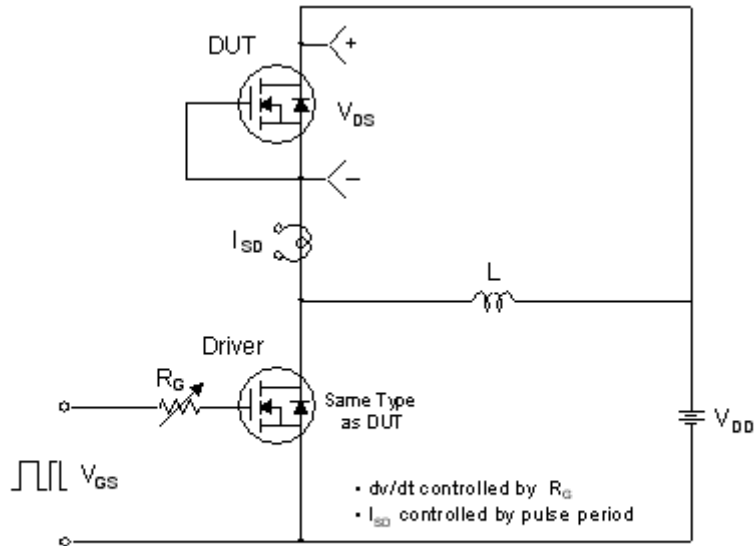
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

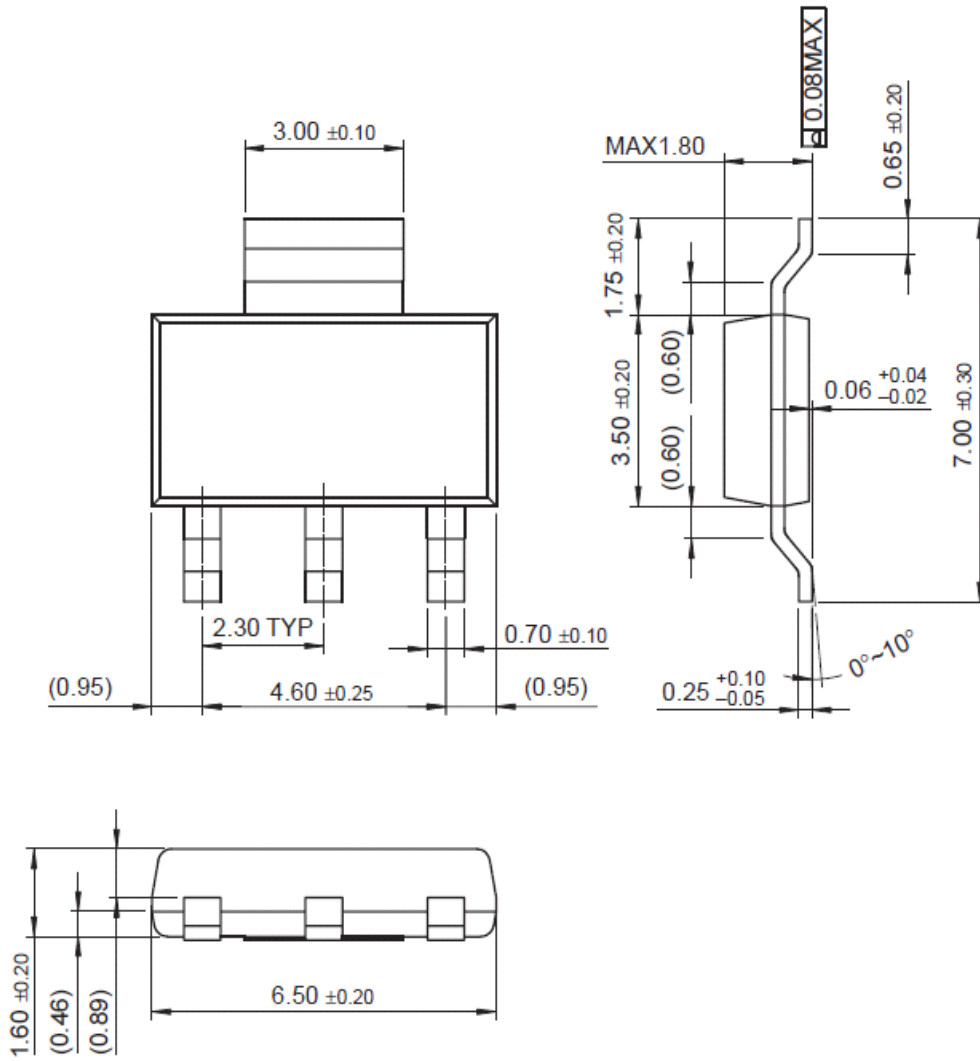


Peak Diode Recovery dv/dt Test Circuit & Waveforms



**Mechanical Dimensions**



**SOT-223**





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